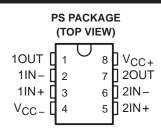
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- Wide Range of Supply Voltages; Single Supply . . . 3 V to 36 V, or Dual Supplies
- Class AB Output Stage
- High-Impedance N-Channel-JFET Input Stage . . . $10^{12} \Omega$ Typ
- Internal Frequency Compensation
- Short-Circuit Protection
- Input Common Mode Includes V_{CC}
- Low Input Offset Current . . . 50 pA
- Low Input Bias Current . . . 200 pA Typ



description

The TL092 JFET-input operational amplifier is similar in performance to the MC3403 family, but with much higher input impedance derived from a FET input stage. The N-channel-JFET input stage allows a common-mode input voltage range that includes the negative supply voltage and offers a typical input impedance of $10^{12}\,\Omega$, a typical input offset current of 50 pA, and a typical input bias current of 200 pA. This device is designed to operate from a single supply over a range of 3 V to 36 V. Operation from split supplies also is possible, provided the difference between the two supplies is 3 V to 36 V. Output voltage range is from V_{CC}– to V_{CC+} – 1.3 V, with a load resistor to V_{CC-}.

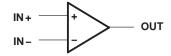
The TL092 is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED DEVICE			
TA	PLASTIC SMALL OUTLINE (PS)			
0°C to 70°C	TL092CPSR			

The PS package is only available taped and reeled. Add the suffix R to device type for ordering (e.g., TL092CPSR).

symbol

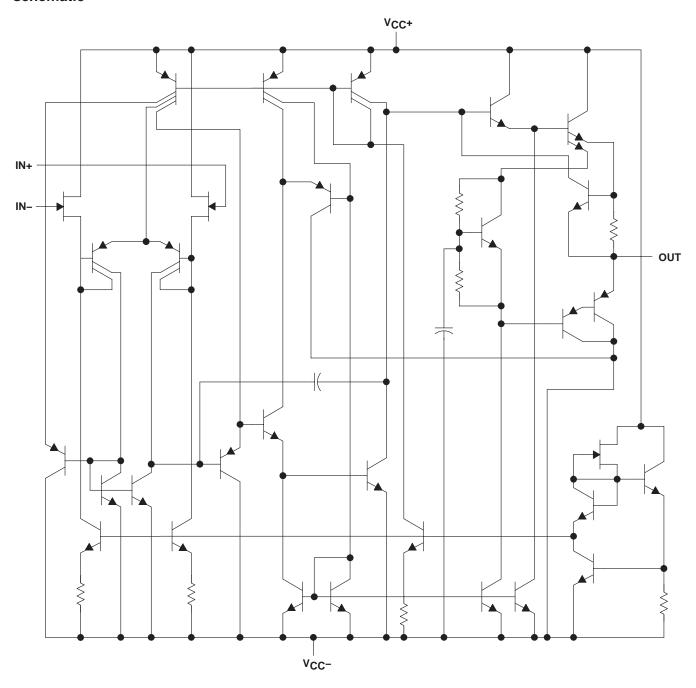




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schematic





TL092 DUAL JFET-INPUT OPERATIONAL AMPLIFIER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V _{CC+} (see Note 1)	18 V
V _{CC} - (see Note 1)	18 V
V _{CC+} with respect to V _{CC-}	36 V
Differential input voltage, V _{ID} (see Note 2)	±36 V
Input voltage, V _I (see Notes 1 and 3)	±18 V
Package thermal impedance, θ_{JA} (see Notes 4 and 5)	95°C/W
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. Differential voltages are at the noninverting input with respect to the inverting input.
 - 3. Neither input must ever be more positive than $\,V_{CC+}$ or more negative than $\,V_{CC-}$ 0.3 V.
 - Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
VCC±	Supply voltage	3	36	V
TA	Operating free-air temperature range	0	70	°C



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electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (all characteristics are specified under open-loop conditions, unless otherwise noted)

PARAMETER		TEST CONDITIONS		TA	MIN	TYP	MAX	UNIT
.,	land offertuality	5 50 0	$R_S = 50 \Omega$			5	15	.,
VIO	Input offset voltage	$R_S = 50 \Omega$					20	mV
αVIO	Temperature coefficient of input offset voltage			25°C		10		μV/°C
. +	level offert comment			25°C		50	200	рА
110‡	Input offset current			Full range			5	nA
. +	Level Idea comment			25°C		200	400	рА
I _{IB} ‡	Input bias current			Full range			10	nA
VICR	Common-mode input voltage range			25°C	V _{CC} - to 12	V _{CC} - to 13		V
	Peak output voltage swing	$R_L = 2 k\Omega$		25°C	±10	±13		
VO(PP)		$R_L = 10 \text{ k}\Omega$		25°C	±12	±13.5		V
. ,		$R_L = 2 k\Omega$ Full range \pm			±10			
Δ	Large-signal differential voltage amplification	$R_L = 2 k\Omega$,	V _O = ±10 V	25°C	20	200		\//\/
AVD				Full range	15			V/mV
ВОМ	Maximum output swing bandwidth	$R_L = 2 k\Omega$, $A_{VD} = 1$,	V _{O(PP)} = 20 V, THD < 5%	25°C		9		kHz
B ₁	Unity gain bandwidth	$R_L = 10 \text{ k}\Omega$,	$V_O = 50 \text{ mV}$	25°C		1		MHz
φm	Phase margin	$R_L = 2 k\Omega$,	C _L = 200 pF	25°C		60°		
rį	Input resistance	f = 20 Hz		25°C		10 ¹²		Ω
r _O	Output resistance	f = 20 Hz		25°C		75		Ω
CMRR	Common-mode rejection ratio	$R_S = 50 \Omega$,	V _{IC} = V _{ICR}	25°C	70	90		dB
kSVR	Supply-voltage rejection ratio (ΔV _{CC} /ΔV _{IO})	$R_S = 50 \Omega$,	$V_{CC\pm} = \pm 3 \text{ V to } \pm 15 \text{ V}$	25°C	75	90		dB
los	Short-circuit output current			25°C		40		mA
Icc	Supply current (per amplifier)	$V_{O} = 0$,	No load	25°C		1.5	2.5	mA

electrical characteristics at specified free-air temperature, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TE	TEST CONDITIONS			MAX	UNIT
V _{IO}	Input offset voltage	$R_S = 50 \Omega$,	V _O = 2.5 V		5	15	mV
lio	Input offset current	V _O = 2.5 V			50	200	рА
I _{IB}	Input bias current	V _O = 2.5 V			200	400	рА
V _{O(PP)}	Peak output voltage swing	$R_L = 10 \text{ k}\Omega$		3.3	3.5		V
		$R_L = 10 \text{ k}\Omega$,	$V_{CC+} = 5 \text{ V to } 30 \text{ V}$	V _{CC+} -1.7			V
AVD	Large-signal differential voltage amplification	$R_L = 2 k\Omega$,	ΔV _O =1.6 V	20	200		V/mV
k _{SVR}	Supply-voltage rejection ratio (ΔV _{CC} /ΔV _{IO})	$R_S = 50 \Omega$,	$V_{CC\pm} = \pm 3 \text{ V to } \pm 15 \text{ V}$	75			dB
Icc	Supply current (per amplifier)	V _O = 2.5 V,	No load		1.5	2.5	mA
V _{O1} /V _{O2}	Channel separation	f = 1 kHz to 20 kHz			120		dB

[†] All typical values are at $T_A = 25$ °C.



[†] All typical values are at T_A = 25°C. ‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

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operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = $25^{\circ}C$

	PARAMETER	TEST CO	MIN	TYP	MAX	UNIT		
SR	Slew rate at unity gain	$V_I = \pm 10 \text{ V (see Figure 1)},$	C _L = 100 pF,	$R_L = 2 k\Omega$		0.6		V/μs
t _r	Rise time	ΔV_{O} = 50 mV (see Figure 1),	C _L = 100 pF,	$R_L = 2 k\Omega$		0.2		μs
t _f	Fall time	C _L = 100 pF,	$R_L = 2 k\Omega$		0.2		μs	
	Overshoot factor	ΔV_{O} = 50 mV (see Figure 1),	C _L = 100 pF,	$R_L = 2 k\Omega$		20%		
	Crossover distortion	$V_{IPP} = 30 \text{ mV}, V_{O(PP)} = 2 \text{ V},$	f = 10 kHz			1%		
Vn	Equivalent input noise voltage	R _S = 100 Ω,	f = 1 kHz			34		nV/√ Hz

PARAMETER MEASUREMENT INFORMATION

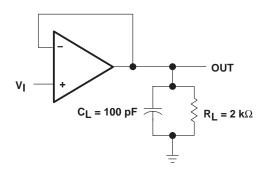


Figure 1. Unity-Gain Amplifier



PACKAGE OPTION ADDENDUM

27-Feb-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL092CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL092CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

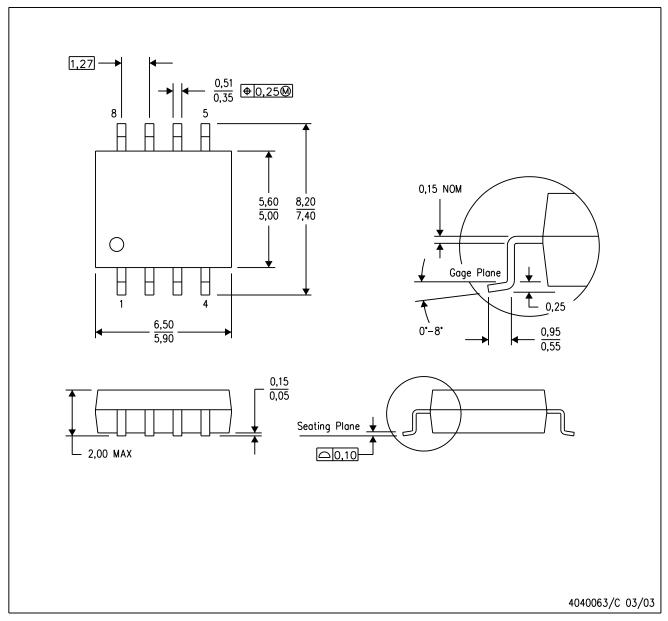
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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